Semiconductor Device Type: STX VQFN 28 4x4x1.0mm Matte Tin

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silicon	7440-21-3	Die	2.32	0.99	23200
Copper	7440-50-8	Leadframe	33.92	14.45	339193
Iron	7439-89-6	Leadframe	0.81	0.35	8121
Zinc	7440-66-6	Leadframe	0.04	0.02	418
Phosphorous	7723-14-0	Leadframe	0.03	0.01	271
Silver	7440-22-4	Leadframe Silver Plating	2.34	1.00	23398
Silver	7440-22-4	Die Attach Epoxy	1.31	0.56	13099
exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	Die Attach Epoxy	0.09	0.04	900
Dodecyl Acrylate	2156-97-0	Die Attach Epoxy	0.09	0.04	900
1,6-Hexanediol Diacrylate	13048-33-4	Die Attach Epoxy	0.01	0.00	90
1-Methyl-2-pyrrolidone	872-50-4	Die Attach Epoxy	0.00	0.00	11
Epoxy Resin	Trade Secret	Mold Compound	4.55	1.94	45528
Phenol Resin	Trade Secret	Mold Compound	2.85	1.21	28455
Metal Hydroxide	Trade Secret	Mold Compound	0.85	0.36	8536
Carbon Black	1333-86-4	Mold Compound	0.28	0.12	2845
Silica Fused	60676-86-0	Mold Compound	48.37	20.61	483734
Gold	7440-57-5	Bond Wire	0.37	0.16	3700
Tin	7440-31-5	Lead Finish Plating	1.76	0.75	17600
		TOTALS:	**100.00**	**42.60**	**1,000,000**

42.60 mg Total Mass

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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Package Homogeneous Materials

0.99	**(mg) Total**	**Die**	**% of Total Weight**	**2.32**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
14.82	**(mg) Total**	**Leadframe**	**% of Total Weight**	**34.80**
	Copper	7440-50-8	97.47	
	Iron	7439-89-6	2.33	
	Zinc	7440-66-6	0.12	
	Phosphorous	7723-14-0	0.08	
		Total	**100.00**	
1.00	**(mg) Total**	**Leadframe Silver Plating**	**% of Total Weight**	**2.34**
	Silver	7440-22-4	100.00	
		Total	**100.00**	
0.64	**(mg) Total**	**Die Attach Epoxy**	**% of Total Weight**	**1.50**
	Silver	7440-22-4	87.33	
	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	6.00	
	Dodecyl Acrylate	2156-97-0	6.00	
	1,6-Hexanediol Diacrylate	13048-33-4	0.60	
	1-Methyl-2-pyrrolidone	872-50-4	0.08	
		Total	**100.00**	
24.24	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**56.91**
	Epoxy Resin	Trade Secret	8.00	
	Phenol Resin	Trade Secret	5.00	
	Metal Hydroxide	Trade Secret	1.50	
	Carbon Black	1333-86-4	0.50	
	Silica Fused	60676-86-0	85.00	
		Total	**100.00**	
0.16	**(mg) Total**	**Bond Wire**	**% of Total Weight**	**0.37**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
0.75	**(mg) Total**	**Lead Finish Plating**	**% of Total Weight**	**1.76**
	Tin	7440-31-5	100.00	
42.60		**Total**	**100.00**	100.00